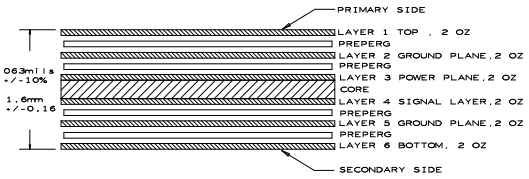
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	INITIAL RELEASE	04/11/15	RAJA
2	ALPHA RELEASE	01/12/15	RAJA
3	BETA RELEASE	22/12/15	RAJA



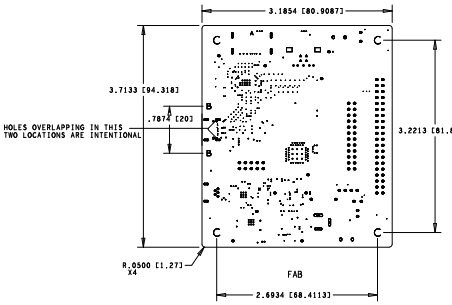
NOTE: 6 MIL 8 MIL SPACING TRACES ON LAYER 1 DIFFERENTIAL IMPEDANCE CONTROLLED TO 90 OHMS +/- 10% TESTED

NOTE: 6 MIL 10.3 MIL SPACING TRACES ON LAYER 4 DIFFERENTIAL IMPEDANCE CONTROLLED TO 100 OHMS +/- 10% TESTED

NOTE: 6 MIL 8 MIL SPACING TRACES ON LAYER 6 DIFFERENTIAL IMPEDANCE CONTROLLED TO 90 OHMS +/- 10% TESTED

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLESS NIKEL & IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY. FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WARP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILLIMETERS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	0.2032	+0.0762/-0.0762	PLATED	233
·	0.254	+0.0/-0.254	PLATED	41
·	0.254	+0.0762/-0.0762	PLATED	173
·	0.381	+0.0762/-0.0762	PLATED	5
◦	0.7112	+0.0762/-0.0762	PLATED	5
+	0.7782	+0.0762/-0.0762	PLATED	5
△	0.9982	+0.0762/-0.0762	PLATED	4
◈	1.016	+0.0762/-0.0762	PLATED	98
○	1.3	+0.0762/-0.0762	PLATED	4
□	2.3762	+0.0762/-0.0762	PLATED	2
·	0.8	+0.050B/-0.050B	NON-PLATED	1
A	1.4	+0.050B/-0.050B	NON-PLATED	1
B	2.2	+0.050B/-0.050B	NON-PLATED	2
C	3.175	+0.050B/-0.050B	NON-PLATED	4
◊	1.2498±0.7	+0.0762/-0.0762	PLATED	2
▭	1.8999±0.5999	+0.0762/-0.0762	PLATED	2
▭	1.8999±0.701	+0.0762/-0.0762	PLATED	2
▭	2.0±0.7	+0.0762/-0.0762	PLATED	2
▯	2.2761±0.6761	+0.0762/-0.0762	PLATED	4
▯	3.175±0.889	+0.0762/-0.0762	PLATED	1
⬭	3.175±0.889	+0.0762/-0.0762	PLATED	1
⬭	3.683±1.143	+0.0762/-0.0762	PLATED	1
✦	0.8±0.6	+0.050B/-0.050B	NON-PLATED	1

UNLESS OTHERWISE SPECIFIED	SIGNATURES		DATE
DIMENSIONS ARE IN INCHES	DRAWN :	HUSAIN	22/12/15
TOLERANCES ON: ANGLES +/- 2°	CHECKED :	RAJA	22/12/15
2 PL DECIMALS +/- .010	ENGRG :	RAGO	22/12/15
3 PL DECIMALS +/- .005	ISSUED		
THIRD ANGLE PROJECTIONS			

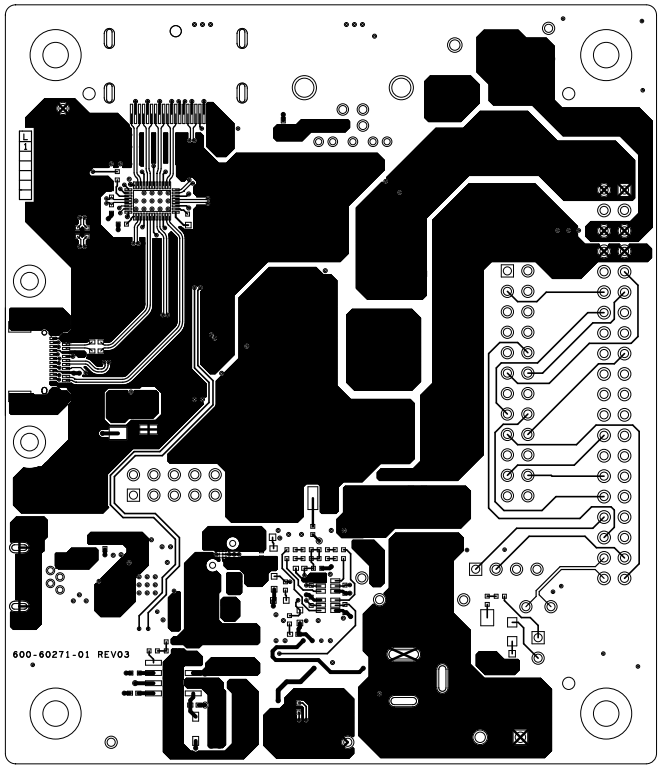
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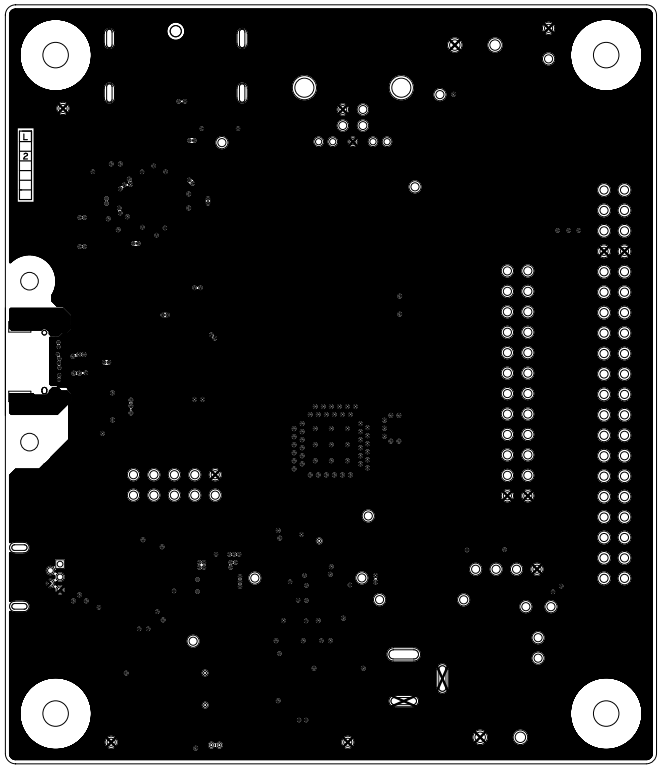
FABRICATION DRAWING
CCG EVK BASE BOARD

SIZE	FSCM NO	DWG NO	REV
C		610-60275-01	03

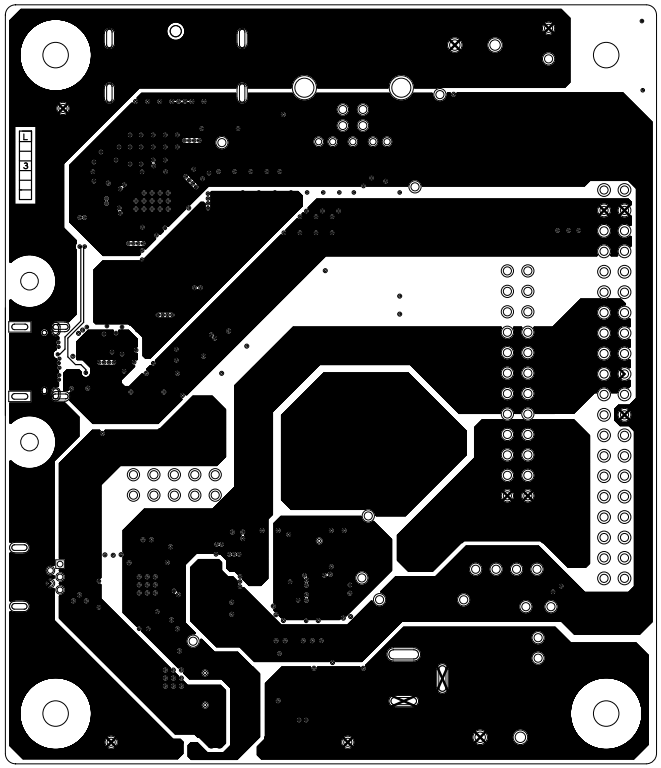
SCALE: 1/1 SHEET: 1 OF 1



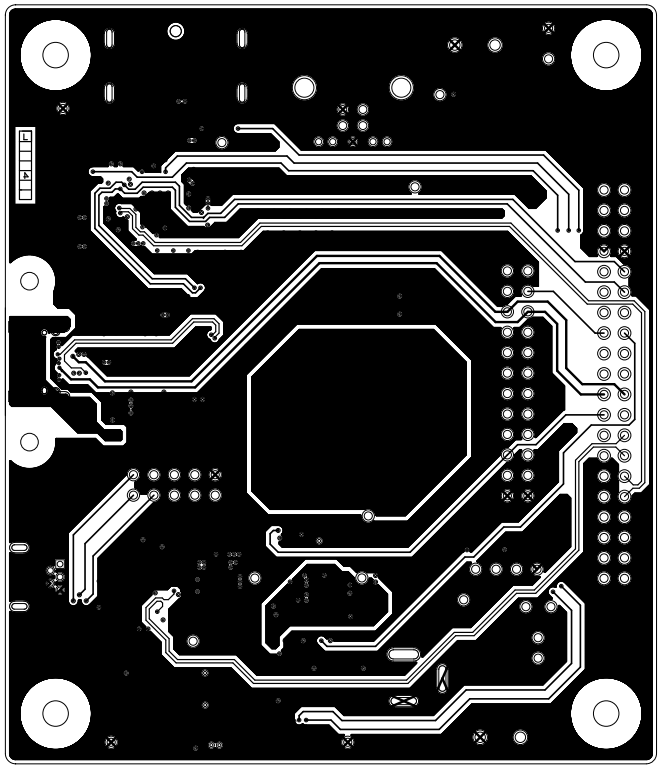
600-60271-01 REV03 PRIMARY SIDE



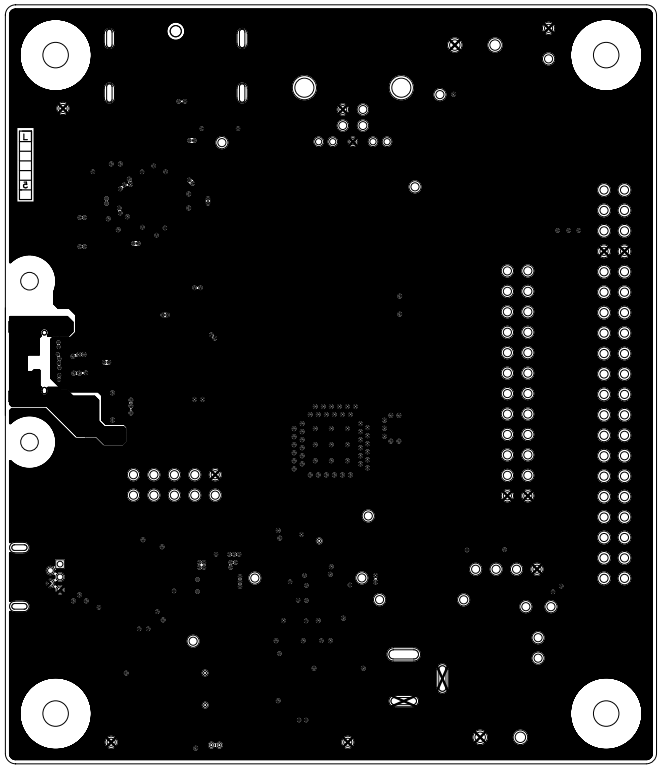
600-60271-01 REV03 GROUND1 LAYER



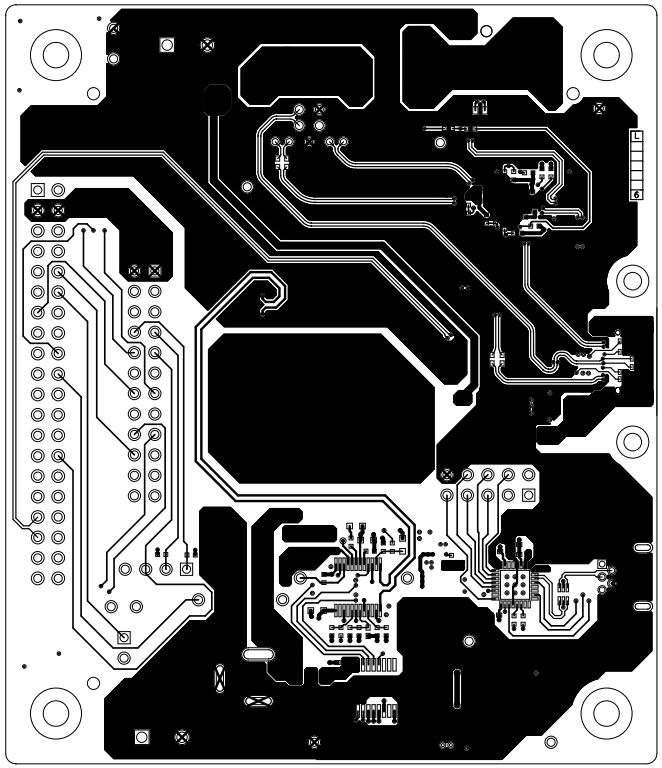
600-60271-01 REV03 POWER1 LAYER



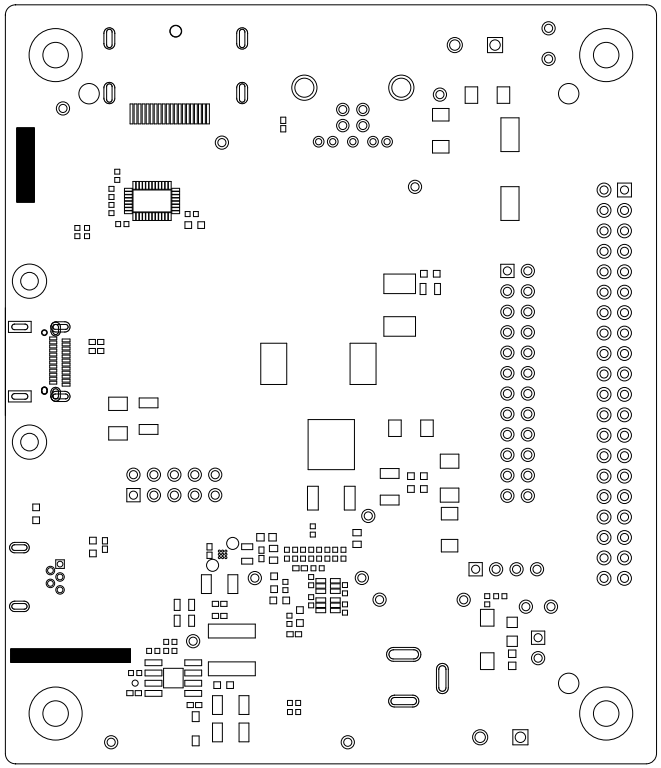
600-60271-01 REV03 SIGNAL1 LAYER



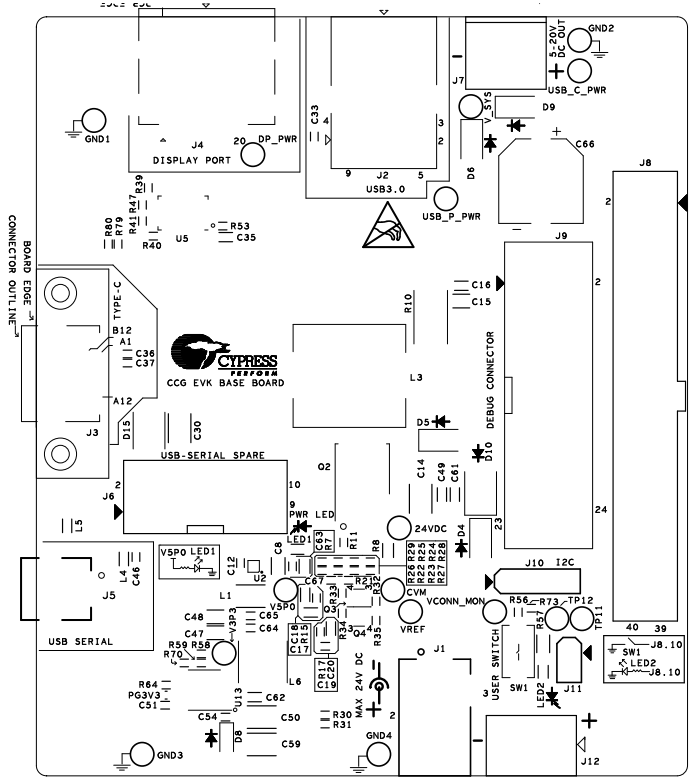
600-60271-01 REV03 GROUND2 LAYER



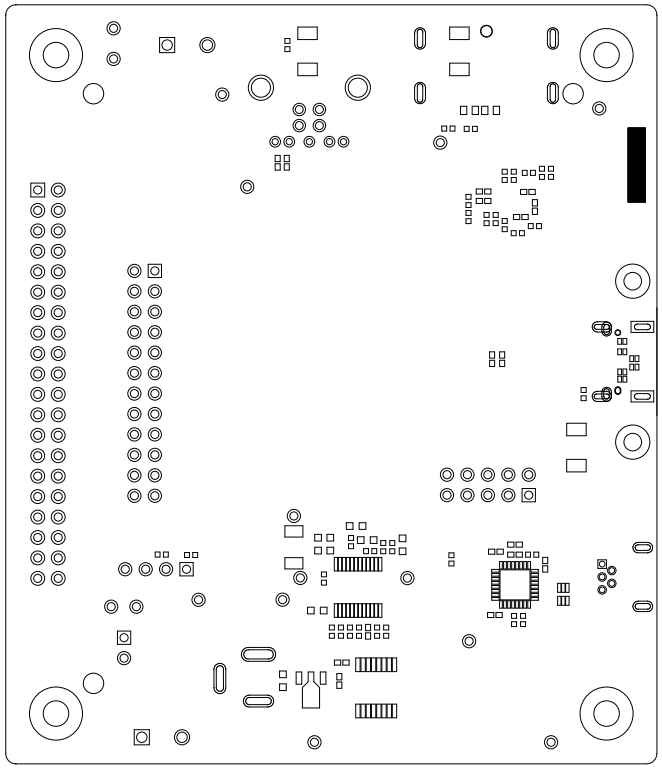
600-60271-01 REV03 SECONDARY SIDE



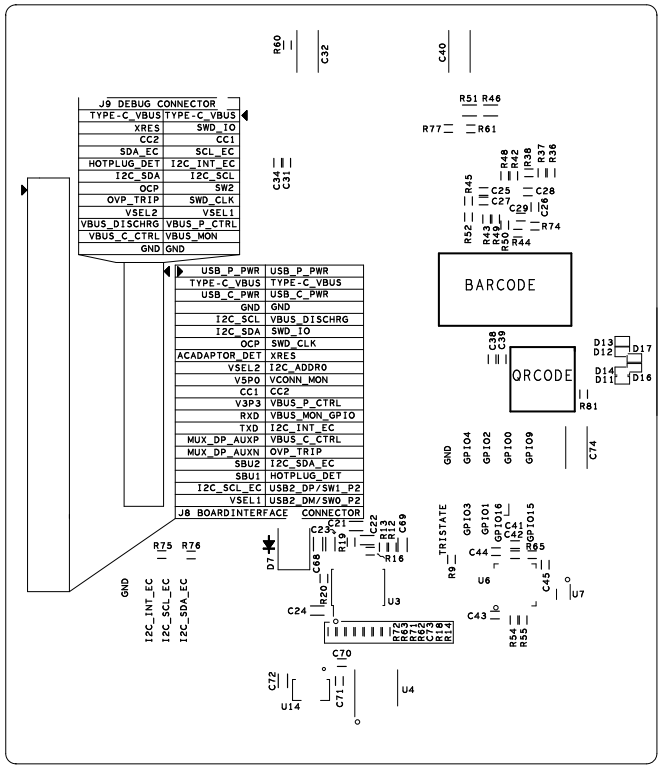
600-60271-01 REV03 PRIMARY SOLDERMASK



600-60271-01 REV03 PRIMARY SILKSCREEN



600-60271-01 REV03 SECONDARY SOLDER MASK



600-60271-01 REV03 SECONDARY SILKSCREEN